

FIG. 1 is a perspective view of a semiconductor device 101. The device includes a substrate 101a, a first layer 101b, and a second layer 102. A central region 103 is defined by a raised structure. A top layer 107 is shown above the device. A circular region 104 is indicated on the left side of the device.



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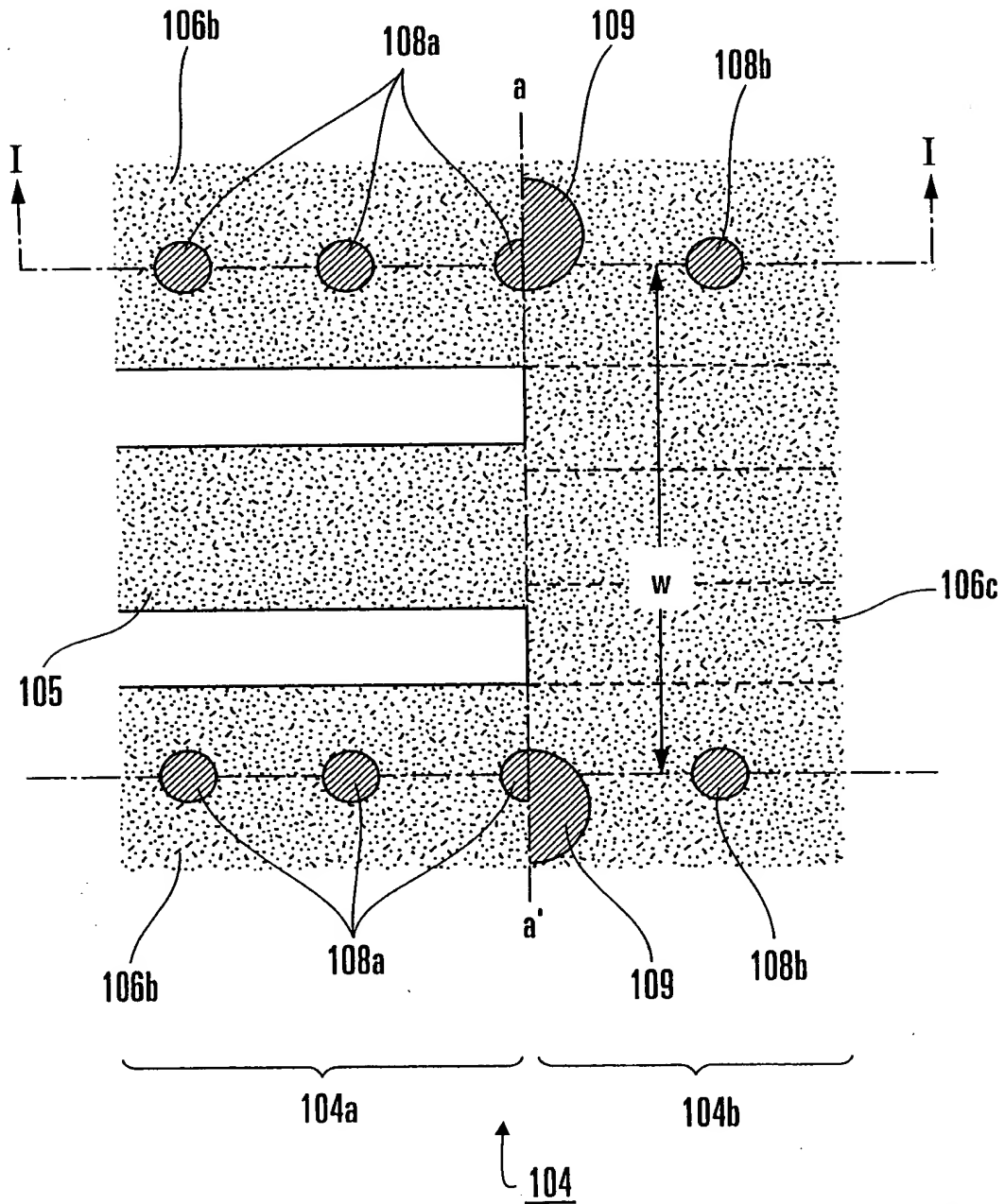


FIG. 3